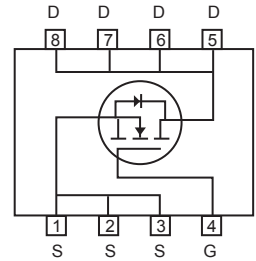
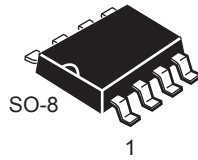


Single N-Channel Enhancement Mode Field Effect Transistor

PRELIMINARY

FEATURES

- 100V, 3.4A, $R_{DS(ON)} = 120m\Omega$ @ $V_{GS} = 10V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.
- Surface mount Package.



ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

| Parameter | Symbol | Limit | Units |
|---------------------------------------|----------------|------------|------------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 3.4 | A |
| Drain Current-Pulsed ^a | I_{DM} | 13.6 | A |
| Maximum Power Dissipation | P_D | 2.5 | W |
| Operating and Store Temperature Range | T_J, T_{stg} | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Parameter | Symbol | Limit | Units |
|--|-----------------|-------|--------------|
| Thermal Resistance, Junction-to-Ambient ^b | $R_{\theta JA}$ | 50 | $^\circ C/W$ |



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|--|--------------|--|-----|-----|------|-----------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 100 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 100V, V_{GS} = 0V$ | | | 1 | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{GS} = 20V, V_{DS} = 0V$ | | | 100 | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{GS} = -20V, V_{DS} = 0V$ | | | -100 | nA |
| On Characteristics ^c | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS} = V_{DS}, I_D = 250\mu A$ | 2 | | 4 | V |
| Static Drain-Source On-Resistance | $R_{DS(on)}$ | $V_{GS} = 10V, I_D = 1.7A$ | | 100 | 120 | $m\Omega$ |
| Dynamic Characteristics ^d | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS} = 25V, V_{GS} = 0V, f = 1.0\text{ MHz}$ | | 540 | | pF |
| Output Capacitance | C_{oss} | | | 100 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 22 | | pF |
| Switching Characteristics ^d | | | | | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 50V, I_D = 3.4A, V_{GS} = 10V, R_{GEN} = 25\Omega$ | | 14 | 30 | ns |
| Turn-On Rise Time | t_r | | | 3 | 7 | ns |
| Turn-Off Delay Time | $t_{d(off)}$ | | | 38 | 80 | ns |
| Turn-Off Fall Time | t_f | | | 7.5 | 15 | ns |
| Total Gate Charge | Q_g | $V_{DS} = 80V, I_D = 3.4A, V_{GS} = 10V$ | | 12 | 16 | nC |
| Gate-Source Charge | Q_{gs} | | | 2.5 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 4.2 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current ^b | I_S | | | | 3.4 | A |
| Drain-Source Diode Forward Voltage ^c | V_{SD} | $V_{GS} = 0V, I_S = 3.4A$ | | | 1.2 | V |
| Notes : □ a.Repetitive Rating : Pulse width limited by maximum junction temperature. □ b.Surface Mounted on FR4 Board, $t \leq 10\text{ sec}$. □ c.Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$. □ d.Guaranteed by design, not subject to production testing. | | | | | | |



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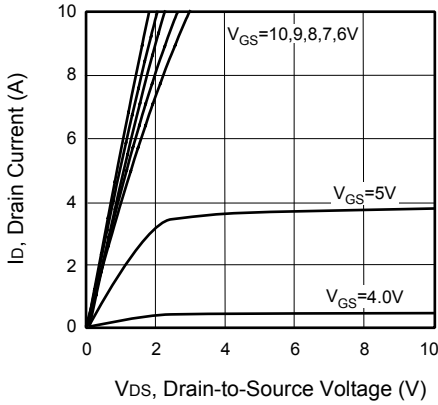


Figure 1. Output Characteristics

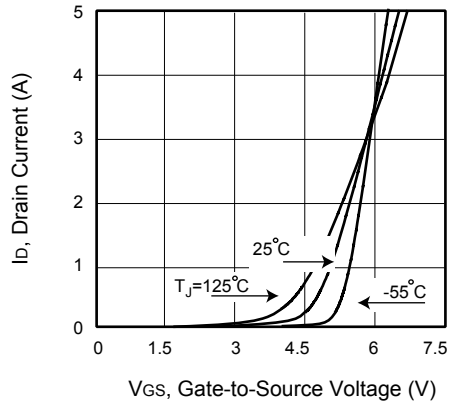


Figure 2. Transfer Characteristics

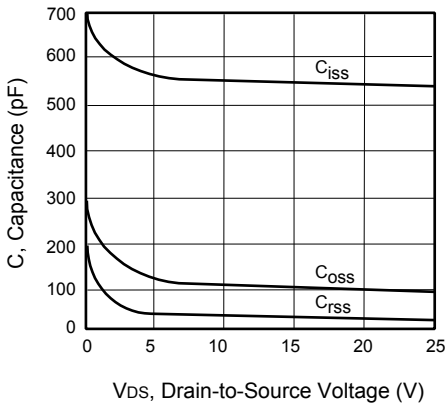


Figure 3. Capacitance

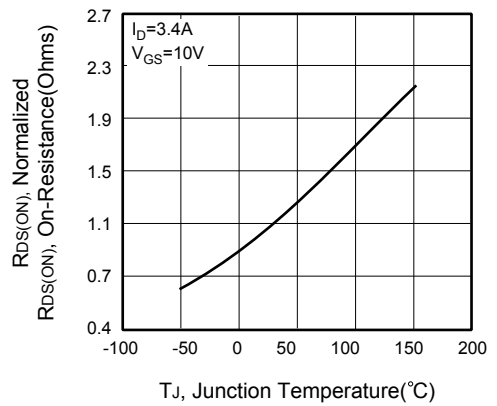


Figure 4. On-Resistance Variation with Temperature

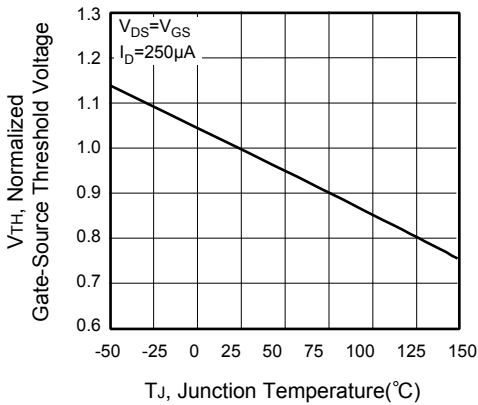


Figure 5. Gate Threshold Variation with Temperature

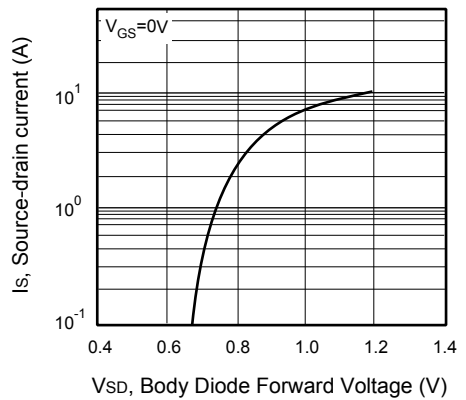


Figure 6. Body Diode Forward Voltage Variation with Source Current



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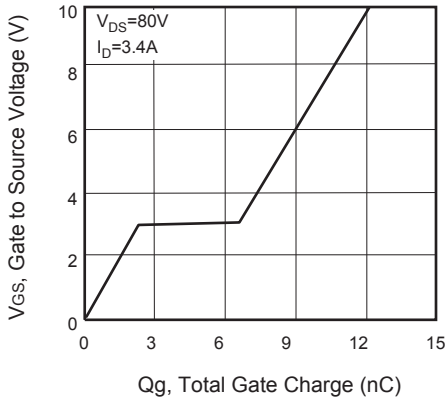


Figure 7. Gate Charge

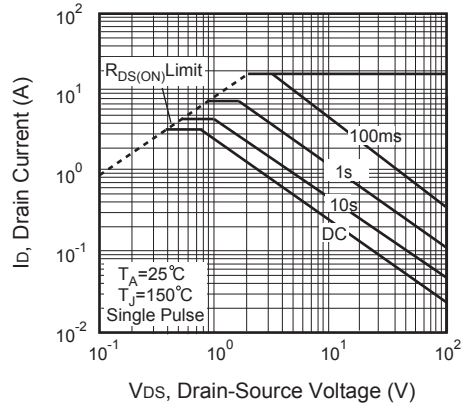


Figure 8. Maximum Safe Operating Area



Figure 9. Switching Test Circuit



Figure 10. Switching Waveforms

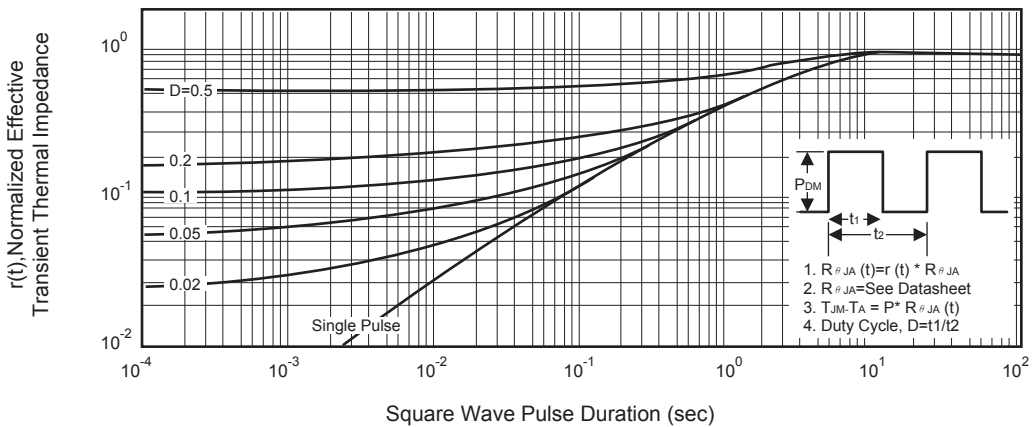


Figure 11. Normalized Thermal Transient Impedance Curve